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GHB-GW20-YG

Features

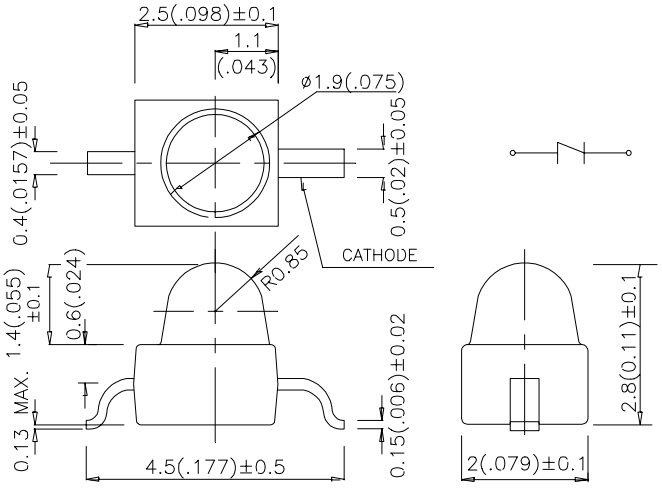
- SUBMINIATURE PACKAGE.
- WIDE VIEWINGANGLE.
- LONG LIFE -SOLID STATE RELIABILITY.
- LOW PACKAGEPROFILE.
- PACKAGE : 1000PCS / REEL.

Description

The Mega Green source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

SUBMINIATURE SOLID STATE LAMP

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is 0.25(0.01") unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	
GHB-GW20-YG	MEGA GREEN (InGaAIP)	WATER CLEAR	280	600	20°

Note:
1. 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

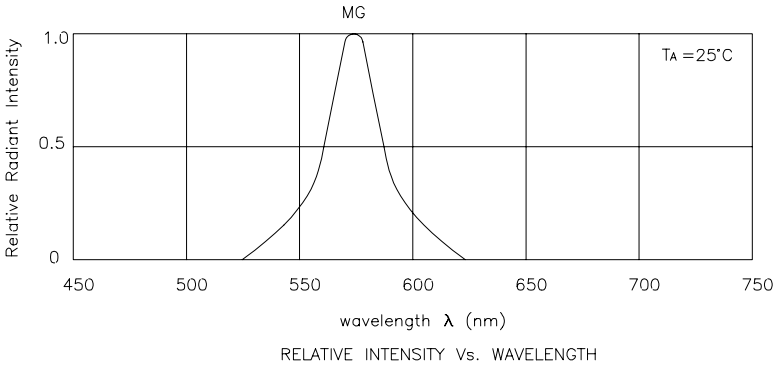
Electrical / Optical Characteristics at T_A=25 C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
peak	Peak Wavelength	Mega Green	574		nm	I_F=20mA
D	Dominate Wavelength	Mega Green	568		nm	I_F=20mA
1/2	Spectral Line Half-width	Mega Green	26		nm	I_F=20mA
C	Capacitance	Mega Green	20		pF	V_F=0V;f=1MHz
V_F	Forward Voltage	Mega Green	2.1	2.5	V	I_F=20mA
I_R	Reverse Current	Mega Green		10	uA	V_R = 5V

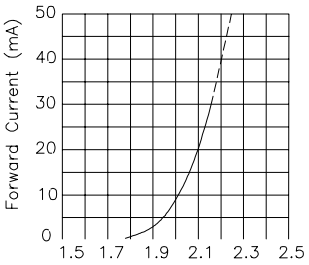
Absolute Maximum Ratings at T_A=25 C

Parameter	Mega Green	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40 C To +85 C	

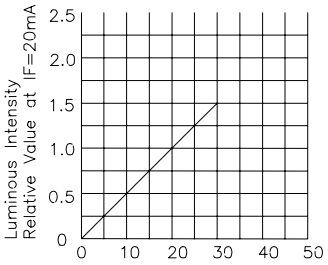
Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



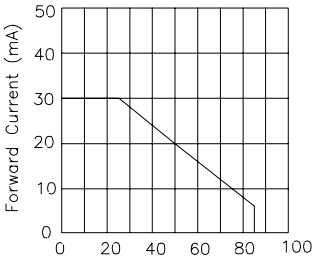
RELATIVE INTENSITY Vs. WAVELENGTH



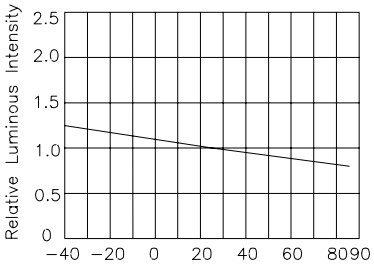
FORWARD CURRENT Vs.
FORWARD VOLTAGE



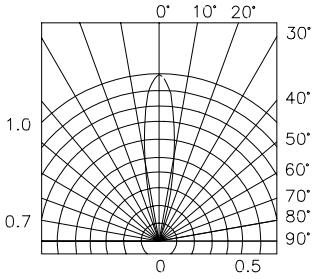
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



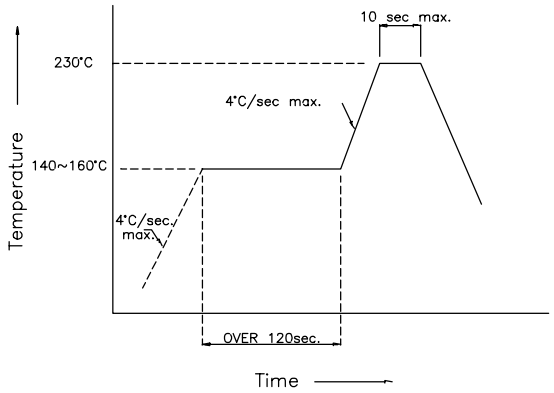
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



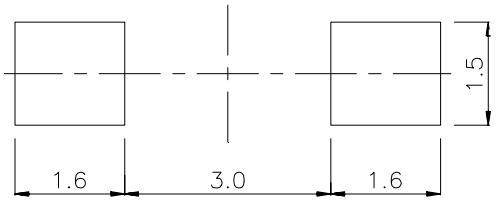
SPATIAL DISTRIBUTION

SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)